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ELECTRONICS

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Jameco Part Number 792757

# **Hex Schmitt Trigger**

The MC14584B Hex Schmitt Trigger is constructed with MOS P-channel and N-channel enhancement mode devices in a single monolithic structure. These devices find primary use where low power dissipation and/or high noise immunity is desired. The MC14584B may be used in place of the MC14069UB hex inverter for enhanced noise immunity to "square up" slowly changing waveforms.

#### **Features**

- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Capable of Driving Two Low-power TTL Loads or One Low-power Schottky TTL Load over the Rated Temperature Range
- Double Diode Protection on All Inputs
- Can Be Used to Replace MC14069UB
- For Greater Hysteresis, Use MC14106B which is Pin–for–Pin Replacement for CD40106B and MM74Cl4
- Pb-Free Packages are Available\*

#### MAXIMUM RATINGS (Voltages Referenced to V<sub>SS</sub>)

	<u> </u>		
Symbol	Parameter	Value	Unit
$V_{DD}$	DC Supply Voltage Range	-0.5 to +18.0	V
V <sub>in</sub> , V <sub>out</sub>	Input or Output Voltage Range (DC or Transient)	-0.5 to V <sub>DD</sub> + 0.5	V
I <sub>in</sub> , I <sub>out</sub>	Input or Output Current (DC or Transient) per Pin	±10	mA
P <sub>D</sub>	Power Dissipation, per Package (Note 1)	500	mW
T <sub>A</sub>	Ambient Temperature Range	-55 to +125	°C
T <sub>stg</sub>	Storage Temperature Range	-65 to +150	°C
T <sub>L</sub>	Lead Temperature (8–Second Soldering)	260	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

 Temperature Derating: Plastic "P and D/DW" Packages: – 7.0 mW/°C From 65°C To 125°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation,  $V_{in}$  and  $V_{out}$  should be constrained to the range  $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{DD}$ .

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either  $V_{SS}$  or  $V_{DD}$ ). Unused outputs must be left open.



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# MARKING DIAGRAMS



PDIP-14 P SUFFIX CASE 646





SOIC-14 D SUFFIX CASE 751A



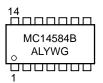


TSSOP-14 DT SUFFIX CASE 948G





SOEIAJ-14 F SUFFIX CASE 965



A = Assembly Location

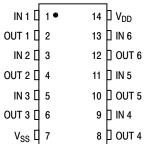
WL, L = Wafer Lot
 YY, Y = Year
 WW, W = Work Week
 G = Pb-Free Indicator

### ORDERING INFORMATION

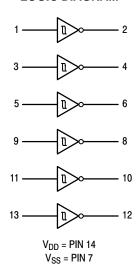
See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

<sup>\*</sup>For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# **PIN ASSIGNMENT**



# **LOGIC DIAGRAM**



## **EQIVALENT CIRCUIT SCHEMATIC**

(1/6 OF CIRCUIT SHOWN)

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MC14584BCP	PDIP-14	500 Units / Rail
MC14584BCPG	PDIP-14 (Pb-Free)	500 Units / Rail
MC14584BD	SOIC-14	55 Units / Rail
MC14584BDG	SOIC-14 (Pb-Free)	55 Units / Rail
MC14584BDR2	SOIC-14	2500 Units / Tape & Reel
MC14584BDR2G	SOIC-14 (Pb-Free)	2500 Units / Tape & Reel
MC14584BDTR2	TSSOP-14*	2500 Units / Tape & Reel
MC14584BF	SOEIAJ-14	50 Units / Rail
MC14584BFEL	SOEIAJ-14	2000 Units / Tape & Reel
MC14584BFELG	SOEIAJ-14 (Pb-Free)	2000 Units / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
\*This package is inherently Pb–Free.

# **ELECTRICAL CHARACTERISTICS** (Voltages Referenced to V<sub>SS</sub>)

			V <sub>DD</sub>	- 5	5°C		25°C		125	5°C	
Characterist	ic	Symbol	Vdc	Min	Max	Min	Typ <sup>(2)</sup>	Max	Min	Max	Unit
Output Voltage V <sub>in</sub> = V <sub>DD</sub>	"0" Level	V <sub>OL</sub>	5.0 10 15	- - -	0.05 0.05 0.05	- - -	0 0 0	0.05 0.05 0.05	- - -	0.05 0.05 0.05	Vdc
V <sub>in</sub> = 0	"1" Level	V <sub>OH</sub>	5.0 10 15	4.95 9.95 14.95	- - -	4.95 9.95 14.95	5.0 10 15		4.95 9.95 14.95	- - -	Vdc
Output Drive Current $ (V_{OH} = 2.5 \text{ Vdc}) $ $ (V_{OH} = 4.6 \text{ Vdc}) $ $ (V_{OH} = 9.5 \text{ Vdc}) $ $ (V_{OH} = 13.5 \text{ Vdc}) $	Source	Іон	5.0 5.0 10 15	- 3.0 - 0.64 - 1.6 - 4.2	- - -	- 2.4 - 0.51 - 1.3 - 3.4	- 4.2 - 0.88 - 2.25 - 8.8	- - -	- 1.7 - 0.36 - 0.9 - 2.4	- - - -	mAdc
$(V_{OL} = 0.4 \text{ Vdc})$ $(V_{OL} = 0.5 \text{ Vdc})$ $(V_{OL} = 1.5 \text{ Vdc})$	Sink	I <sub>OL</sub>	5.0 10 15	0.64 1.6 4.2	- - -	0.51 1.3 3.4	0.88 2.25 8.8	- - -	0.36 0.9 2.4	- - -	mAdc
Input Current		I <sub>in</sub>	15	-	±0.1	_	±0.00001	±0.1	_	±1.0	μAdc
Input Capacitance (V <sub>in</sub> = 0)		C <sub>in</sub>	-	_	-	-	5.0	7.5	_	-	pF
Quiescent Current (Per Package)		I <sub>DD</sub>	5.0 10 15	- - -	0.25 0.5 1.0	- - -	0.0005 0.0010 0.0015	0.25 0.5 1.0	- - -	7.5 15 30	μAdc
Total Supply Current (3) (4) (Dynamic plus Quiescent, Per Package) (C <sub>L</sub> = 50 pF on all outputs, all buffers switching)		Ι <sub>Τ</sub>	5.0 10 15			$I_T = (3$	I.8 μΑ/kHz) f 3.6 μΑ/kHz) f 5.4 μΑ/kHz) f	+ I <sub>DD</sub>			μAdc
Hysteresis Voltage		V <sub>H</sub> <sup>(5)</sup>	5.0 10 15	0.27 0.36 0.77	1.0 1.3 1.7	0.25 0.3 0.6	0.6 0.7 1.1	1.0 1.2 1.5	0.21 0.25 0.50	1.0 1.2 1.4	Vdc
Threshold Voltage Positive–Going		V <sub>T+</sub>	5.0 10 15	1.9 3.4 5.2	3.5 7.0 10.6	1.8 3.3 5.2	2.7 5.3 8.0	3.4 6.9 10.5	1.7 3.2 5.2	3.4 6.9 10.5	Vdc
Negative-Going		V <sub>T</sub>	5.0 10 15	1.6 3.0 4.5	3.3 6.7 9.7	1.6 3.0 4.6	2.1 4.6 6.9	3.2 6.7 9.8	1.5 3.0 4.7	3.2 6.7 9.9	Vdc

Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.
 The formulas given are for the typical characteristics only at 25°C.
 To calculate total supply current at loads other than 50 pF:

$$I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) \text{ Vfk}$$

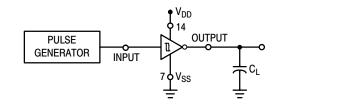
where:  $I_T$  is in  $\mu A$  (per package),  $C_L$  in pF,  $V = (V_{DD} - V_{SS})$  in volts, f in kHz is input frequency, and k = 0.001.

5.  $V_H = V_{T+} - V_{T-}$  (But maximum variation of  $V_H$  is specified as less than  $V_{T+max} - V_{T-min}$ ).

# **SWITCHING CHARACTERISTICS** ( $C_L = 50 \text{ pF}, T_A = 25^{\circ}\text{C}$ )

Characteristic	Symbol	V <sub>DD</sub> Vdc	Min	Typ <sup>(6)</sup>	Max	Unit
Output Rise Time	t <sub>TLH</sub>	5.0	_	100	200	ns
		10	_	50	100	
		15	_	40	80	
Output Fall Time	t <sub>THL</sub>	5.0	_	100	200	ns
		10	_	50	100	
		15	_	40	80	
Propagation Delay Time	t <sub>PLH</sub> , t <sub>PHL</sub>	5.0	_	125	250	ns
		10	_	50	100	
		15	_	40	80	

6. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.



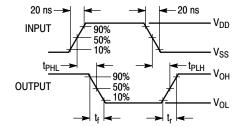
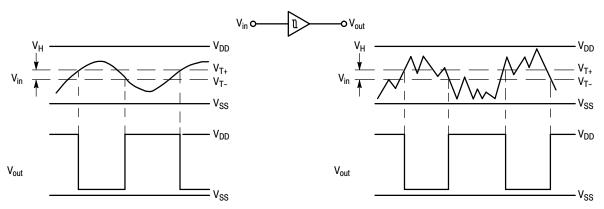


Figure 1. Switching Time Test Circuit and Waveforms



(a) Schmitt Triggers will square up inputs with slow rise and fall times.

(b) A Schmitt trigger offers maximum noise immunity in gate applications.

Figure 2. Typical Schmitt Trigger Applications

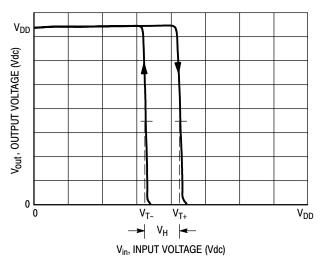
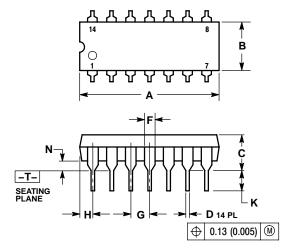


Figure 3. Typical Transfer Characteristics

#### **PACKAGE DIMENSIONS**

# PDIP-14 **P SUFFIX CASE 646-06 ISSUE N**



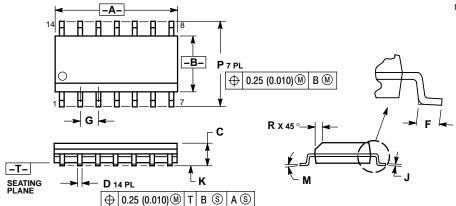


#### NOTES:

- DIMENSIONING AND TOLERANCING
  PER ANSI Y14.5M, 1982.
  CONTROLLING DIMENSION: INCH.
  DIMENSION L TO CENTER OF LEADS
  WHEN FORMED PARALLEL.
- DIMENSION B DOES NOT INCLUDE MOLD FLASH.
- 5. ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.715	0.770	18.16	18.80
В	0.240	0.260	6.10	6.60
C	0.145	0.185	3.69	4.69
D	0.015	0.021	0.38	0.53
F	0.040	0.070	1.02	1.78
G	0.100	BSC	2.54 BSC	
Н	0.052	0.095	1.32	2.41
J	0.008	0.015	0.20	0.38
K	0.115	0.135	2.92	3.43
L	0.290	0.310	7.37	7.87
М		10 °		10 °
N	0.015	0.039	0.38	1.01

## SOIC-14 **D SUFFIX CASE 751A-03 ISSUE G**



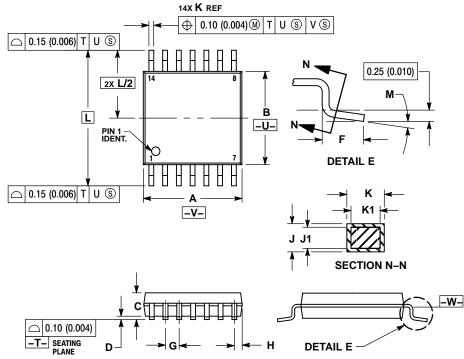
- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
  4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) DED SIDE
- 4. MAAIMUM MICLE PROTROSIGN 6.15 (6.6 PER SIDE.

  5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127
- (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	8.55	8.75	0.337	0.344
В	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27	BSC	0.050	BSC
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
М	0 °	7°	0 °	7°
Р	5.80	6.20	0.228	0.244
P	0.25	0.50	0.010	0.010

#### **PACKAGE DIMENSIONS**

TSSOP-14 **DT SUFFIX** CASE 948G-01 **ISSUE 0** 



- NOTES:

  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
  MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.00) PER SIDE

  - MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.

    4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.

    5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION. CONDITION.
    6. TERMINAL NUMBERS ARE SHOWN FOR

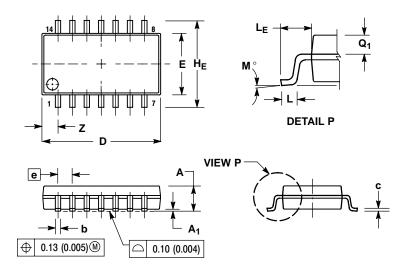
  - REFERENCE ONLY.

    7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE –W–.

	MILLIN	IETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	4.90	5.10	0.193	0.200	
В	4.30	4.50	0.169	0.177	
U		1.20		0.047	
ם	0.05	0.15	0.002	0.006	
F	0.50	0.75	0.020	0.030	
G	0.65	BSC	0.026 BSC		
Η	0.50	0.60	0.020	0.024	
7	0.09	0.20	0.004	0.008	
J1	0.09	0.16	0.004	0.006	
K	0.19	0.30	0.007	0.012	
K1	0.19	0.25	0.007	0.010	
L	6.40	BSC	0.252	BSC	
М	0 °	8°	0°	8°	

# **PACKAGE DIMENSIONS**

SOEIAJ-14 **F SUFFIX** CASE 965-01 **ISSUE 0** 



#### NOTES:

- AUTES:

  1 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

  2 CONTROLLING DIMENSION: MILLIMETER.

  3 DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS (AUT.) NOT EVECED 0.15 (7.000).
- AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.

  4 TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.

  5 THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIN	IETERS	INC	HES		
DIM	MIN	MAX	MIN	MAX		
Α		2.05		0.081		
A <sub>1</sub>	0.05	0.20	0.002	0.008		
b	0.35	0.50	0.014	0.020		
C	0.18	0.27	0.007	0.011		
D	9.90	10.50	0.390	0.413		
E	5.10	5.45	0.201	0.215		
е	1.27	BSC	0.050	0.050 BSC		
HE	7.40	8.20	0.291	0.323		
0.50	0.50	0.85	0.020	0.033		
LE	1.10	1.50	0.043	0.059		
M	0 °	10°	0 °	10°		
Q <sub>1</sub>	0.70	0.90	0.028	0.035		
Z		1.42		0.056		

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